J.E.T. Co., Ltd.

Financial Results for the Fiscal Year Ended December 2024

February 25, 2025

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Agenda

1. Summary of Financial Results for the Fiscal Year Ended December 31, 2024 and Forecast for the Year Ending December 31, 2025
2. Future Growth Strategies and Current Status of Progress
3. Toward Sustainability Management

Appendix

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1. Summary of Financial Results for the Fiscal Year Ended December 31, 2024 Forecast for the Year Ending December 31, 2025

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Results Summary

Startups of new cleaning equipment were low in the 1Q; recovered in the 2Q; remained steady with Chinese foundries but stagnated with Korean memory makers, whose investment halted, in the 3Q; and were postponed with the Korean memory makers and the Chinese foundries in the 4Q. As a result, sales and profit for the current consolidated accounting period decreased compared to last year.

Net sales	Operating profit	Ordinary profit	Net profit
17,880 million JPY	789 million JPY	662 million JPY	318 million JPY
YoY -28.4%	YoY -69.8%	YoY -72.9%	YoY -80.7%

- ✓ **The economic environment remains uncertain due to geopolitical factors such as intensifying trade friction between the U.S. and China, prolonged conflict in Ukraine, and instability in the Middle East, as well as the impact of the U.S. presidential election. Stagnation of consumption of electronics products also continues.**
- ✓ **Regarding the Chinese market, reaction to increased investment in new equipment for mature-generation semiconductors for the past few years caused stagnation of equipment utilization rates and thereby slowed the investment of the foundries in China.**
- ✓ **With memories, prices of DRAM and NAND flash memories fell, which caused weakening of investment.**

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Consolidated Results

Amid declining sales, planned cost reductions (material costs, outsourcing costs, etc.) did not proceed as expected, and efforts to curb SG&A expenses did not result in reductions.

Unit (millions of JPY)	Fiscal year ended December 2023	Sales ratio (%)	Fiscal year ended December 2024	Sales ratio (%)	YoY (%)
Net sales	24,984	—	17,880	—	-28.4%
Gross profit	5,535	22.2%	3,711	20.8%	-32.9%
SG&A expenses	2,921	11.7%	2,922	16.3%	0.0%
Operating profit	2,613	10.5%	789	4.4%	-69.8%
Ordinary profit	2,444	9.8%	662	3.7%	-72.9%
Net profit	1,651	6.6%	318	1.8%	-80.7%

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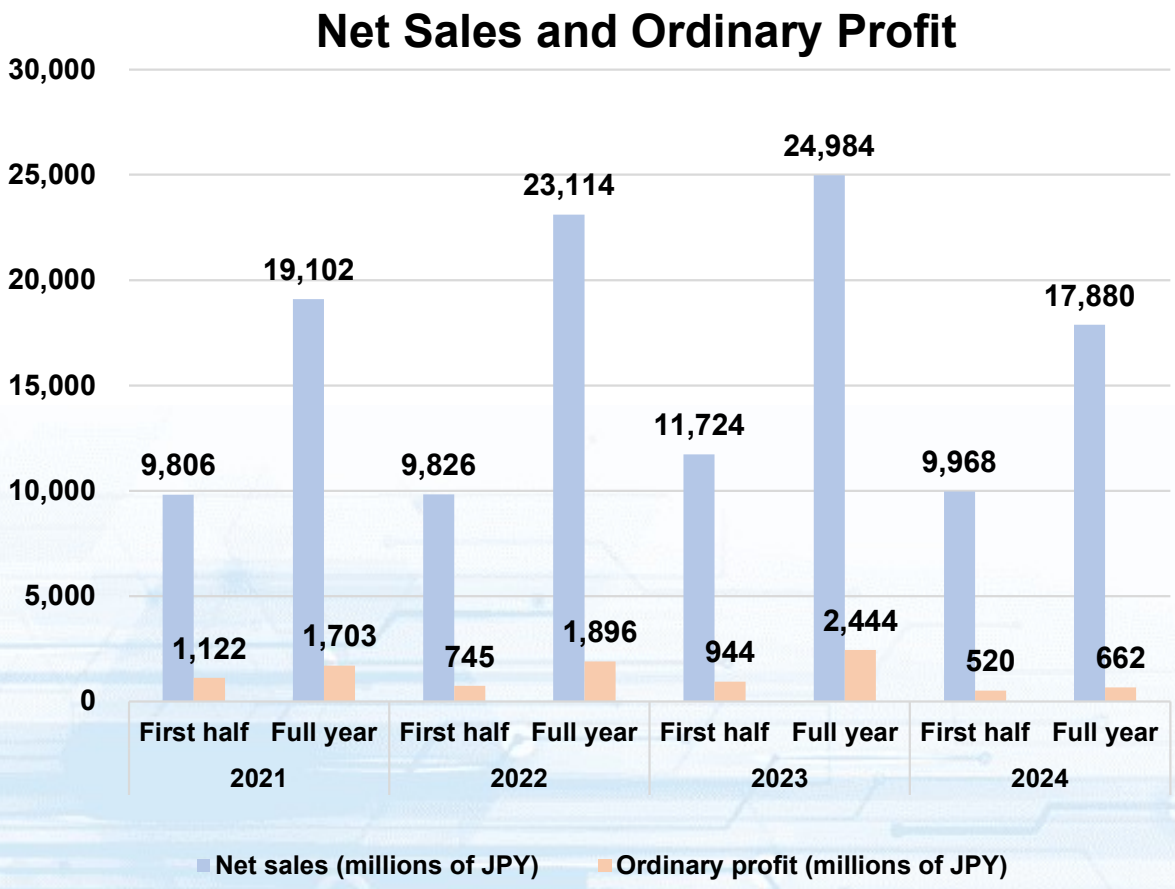
Consolidated Balance Sheet

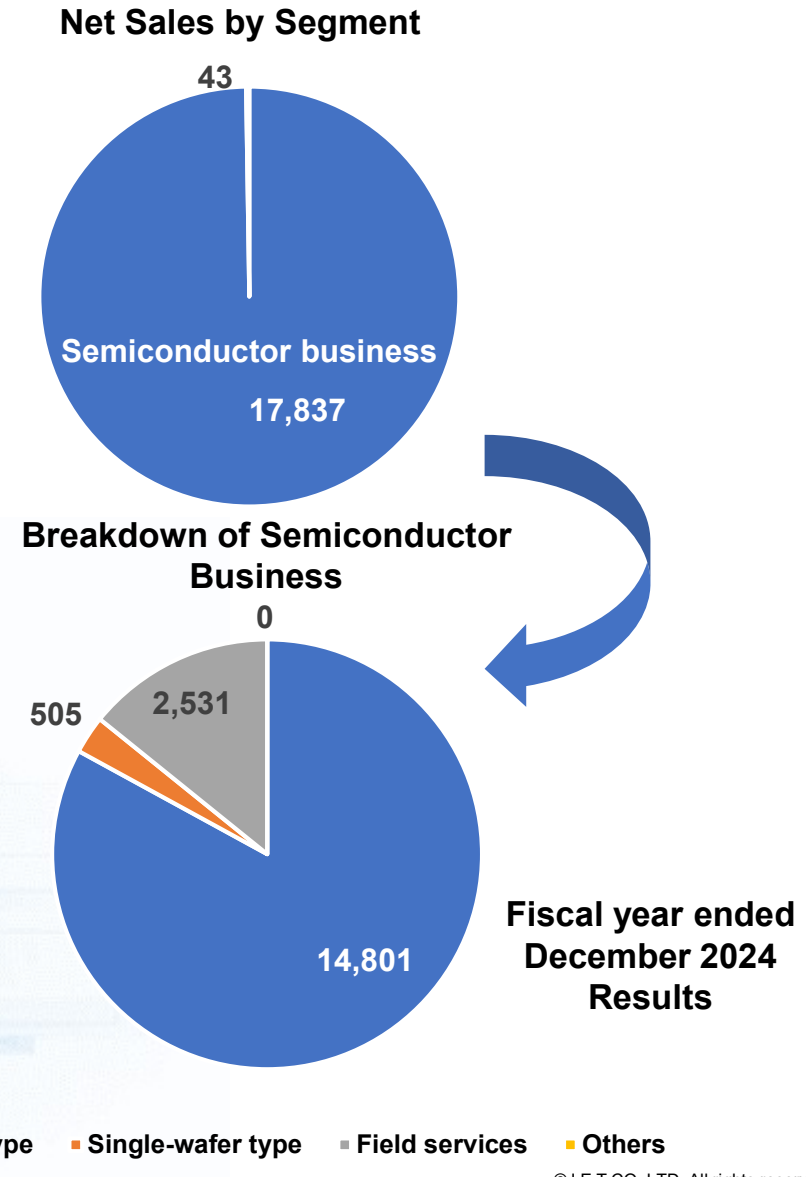
Unit (millions of JPY)	Fiscal year ended December 2023	Fiscal year ended December 2024	Increase/ Decrease	Main factors of change
Current assets	27,068	23,824	-3,244	Decrease in "Cash and Deposits" and "Work in Process"
Property, plant and equipment	954	831	-123	
Intangible assets	56	101	45	
Investments and other assets	695	734	39	
Total assets	28,774	25,491	-3,283	
Current liabilities	11,496	8,570	-2,926	Decrease in Advances Received
Non-current liabilities	4,866	4,451	-415	Decrease in long-term borrowings
Total liabilities	16,362	13,021	-3,341	
Total net assets	12,411	12,469	58	
Total liabilities and net assets	28,774	25,491	-3,283	

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Net Sales and Ordinary Profit and Composition of Net Sales

Performance hit a plateau due to a delay in start-up of cleaning equipment, etc.



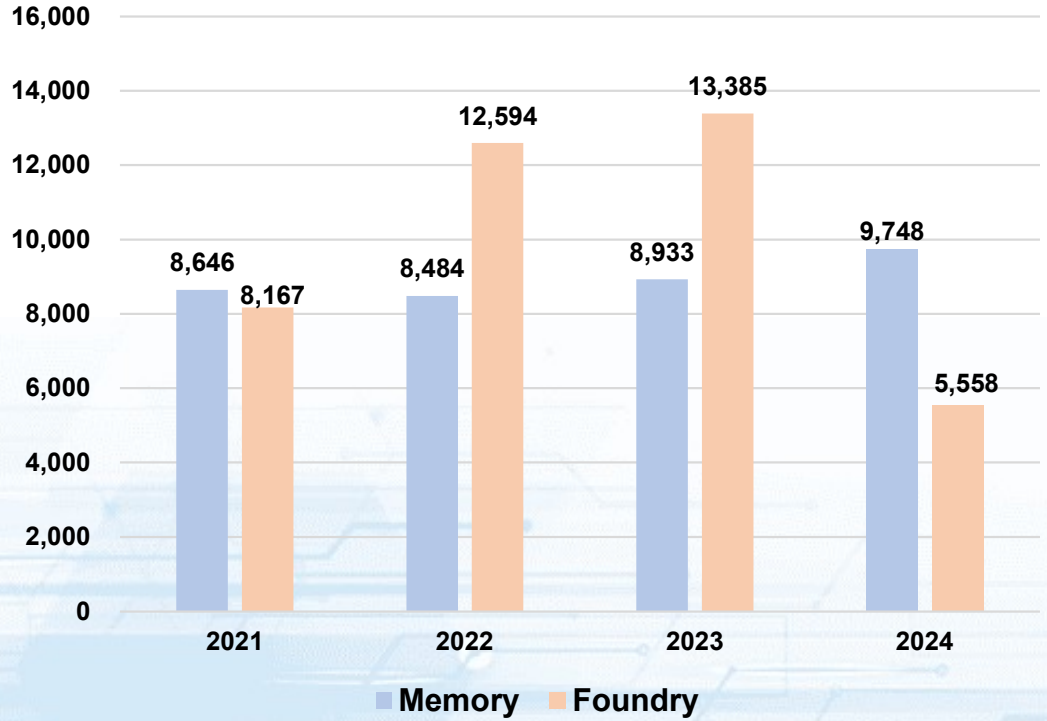


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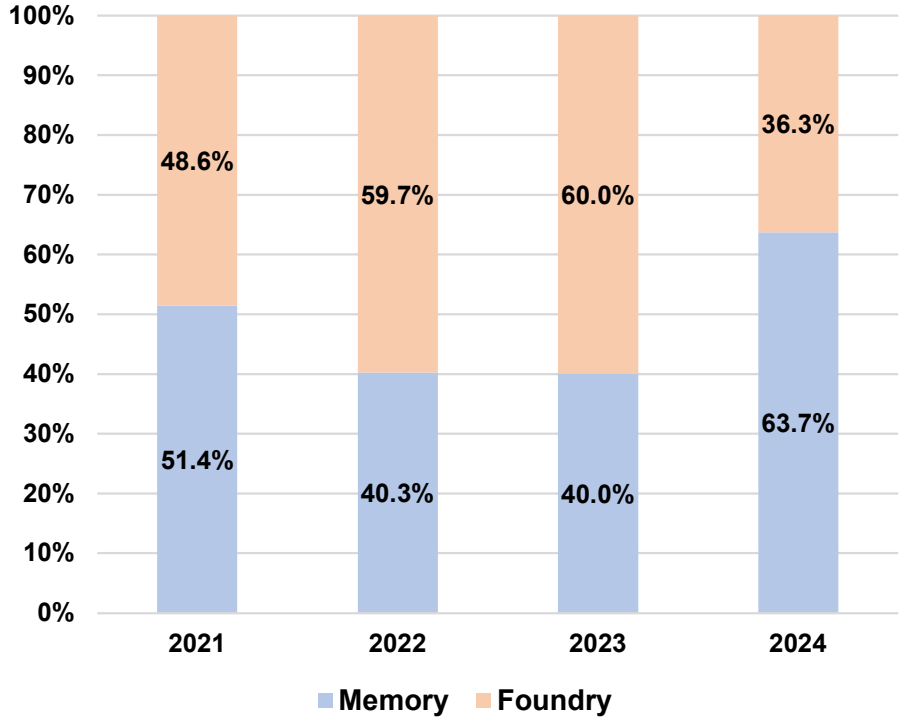
Equipment Net Sales (by Shipping Destination)

By shipping destination, as mentioned above, net sales to foundries struggled.

Trend in Equipment Net Sales by Shipping Destination



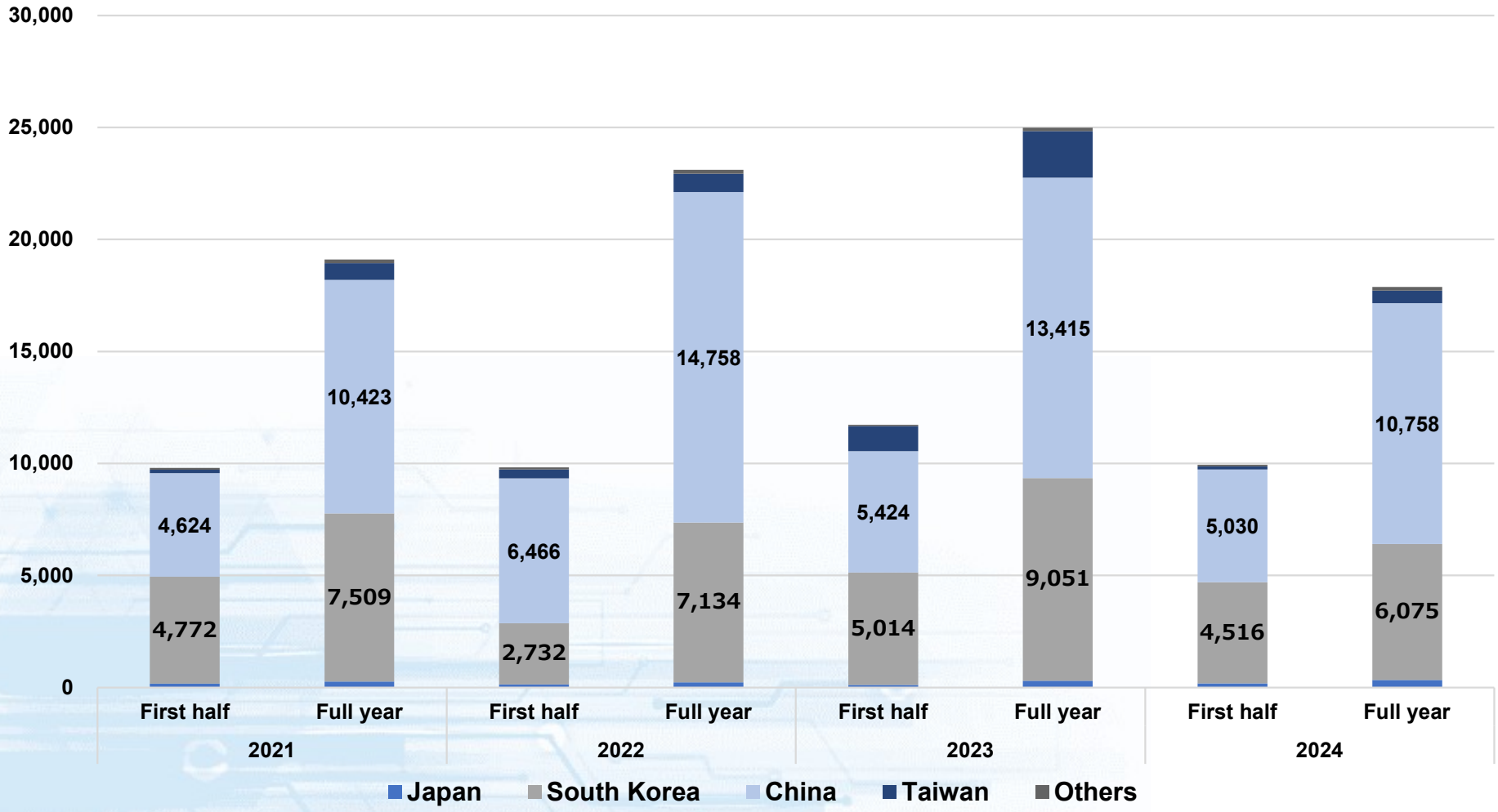
Trend in Equipment Net Sales Composition by Shipping Destination



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Trend in Net Sales by Region

Net sales declined in both China and Korea

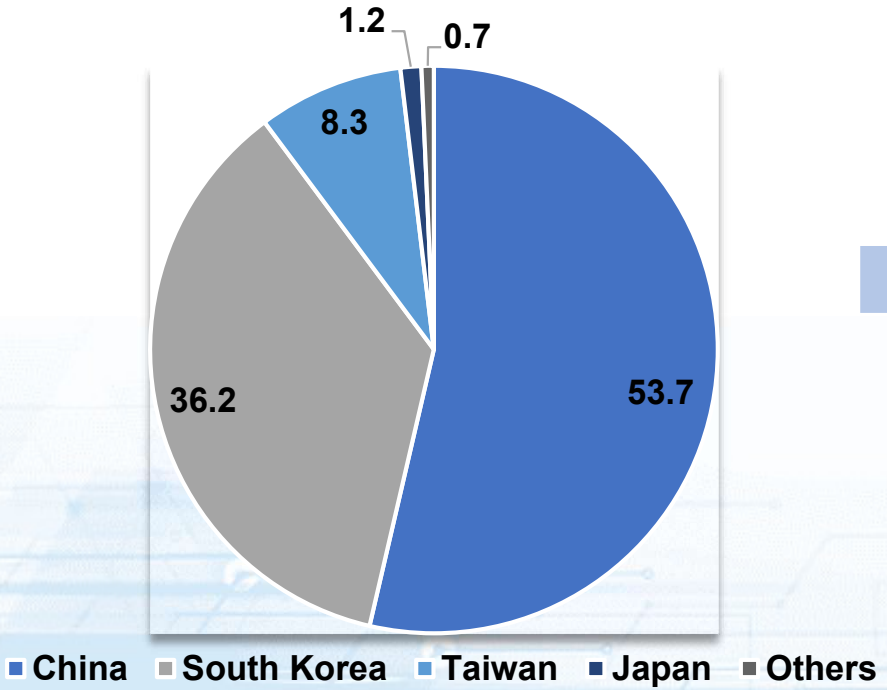


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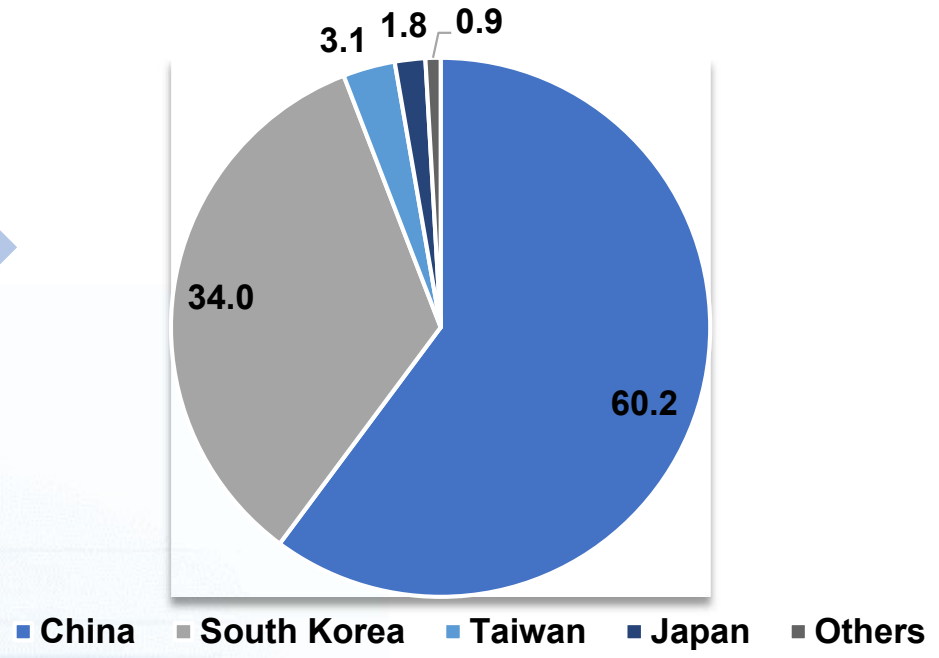
Trend in Net Sales Composition by Region, YoY Comparison

China's share increased in terms of the composition.

* We aim to achieve a composition ratio of 25% each for China, Taiwan, South Korea, and the United States + Japan, in the future.



Fiscal year ended December 2023 Unit: %



Fiscal year ended December 2024 Unit: %

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Topics for the Fiscal Year Ended December 2024 (1)

Despite challenging financial results, several achievements were realized for the next stage of growth.

1. **Awarded a contract for R&D of the next-generation semiconductor manufacturing technology from Rapidus**

   Completed R&D work (α machine)
   Transitioned to R&D work related to prototype equipment manufacturing fabrication (β machine), the equipment to be delivered in 2025
   Aiming to deliver our equipment to mass production lines in 2027

2. **Awarded Subsidy for Large-Scale Growth Investment in Labor-Saving and Other Measures to Raise Wages for Small- and Medium-Sized Enterprises (SMEs)**

   * **Realization of Expansion of Production Capacity, Improvement of Productivity and Acceleration of Research and Development through Construction of New Head Office Plant project**

   The Board of Directors resolved to acquire a site of approximately 30,000 square meters in Asakuchi City, Okayama Prefecture, adjacent to the town of Satosho, where the Head Office is located. The land is to be transferred in the summer of 2025, Released on December 13, 2024

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Topics for the Fiscal Year Ended December 2024 (2)

3. **Sales of strategic model BW3500 started**

   Batch-type 300-mm wafer cleaning equipment
   BW3500, the successor to the BW3000, is expected to stimulate demand for replacement of other companies' products with an eye on production equipment for 28-nm and beyond, as well as demand for replacement of our own productsIntention to establish technological superiority over emerging local manufacturers
   Currently accepting orders and inquiries in China and Korea

4. **Announced Sustainability Management Policy**

   Released on December 13, 2024

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Fiscal Year Ending December 2025, Full-Year Market Environment Outlook

Challenging environment continues

- ✓ Although interest rate hikes and inflation in the U.S. and Europe are slowing, the environment remains uncertain due to soaring raw material and energy prices, continued economic slowdown in the Chinese market, geopolitical factors, and the inauguration of President Trump.
- ✓ Foundry operation rates stagnated due to stagnant global consumption of electronics products and EVs.
- ✓ As for memory, DRAM prices, which had temporarily recovered, are falling, and NAND flash memory is also suffering.

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Full-Year Forecast for the Year Ending December 31, 2025

Despite the difficult environment, we aim to achieve growth in both sales and profit through the following measures.
We will focus on preparing an organization and developing equipment for the next leap forward.

Net sales	Operating profit	Ordinary profit	Net profit
18,820 million JPY YoY +5.2%	790 million JPY YoY +0.0%	690 million JPY YoY +4.0%	370 million JPY YoY +16.0%

- ✓ **Making stronger proposals for new wafer cleaning equipment to Korean manufacturers, who implement their investment plans regardless of market conditions in response to higher DRAM capacity and increasing layers of NAND flash memories.**
- ✓ **Strengthen new customer development in the U.S. through the U.S. subsidiary**
- ✓ **Strengthen customer development for sensors, automotive semiconductors, etc. in the Japanese market**
- ✓ **Expand sales of BW3500 to Chinese market**

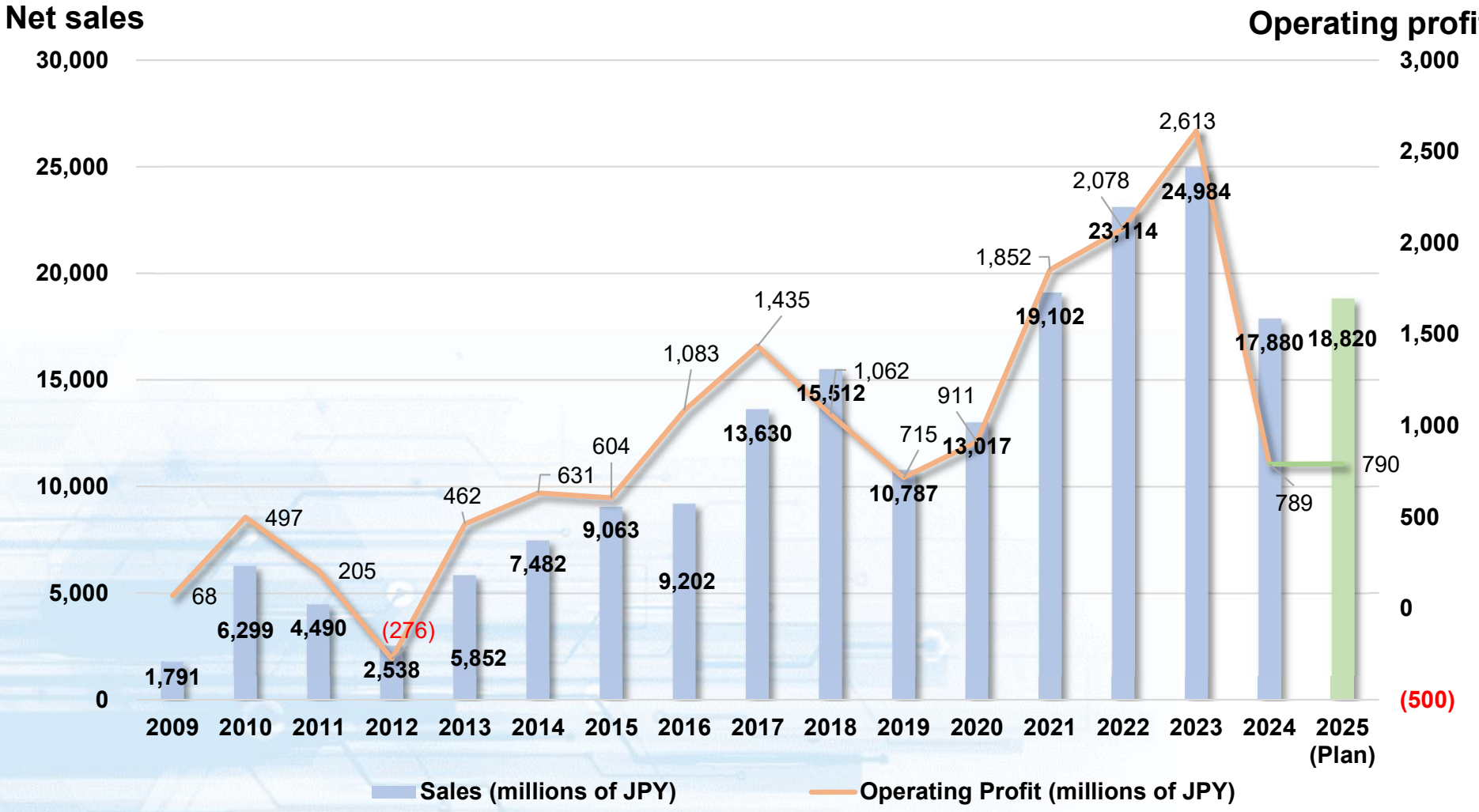
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2. Future Growth Strategies and Current Status of the Progress

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Trends in the Long-Term Consolidated Results (Net Sales and Operating Profit)

While being affected by the silicon cycle, our net sales and operating profit have grown up to now as the demand for semiconductors increased
2024 and 2025 will be years of patience but medium- to long-term growth is expected

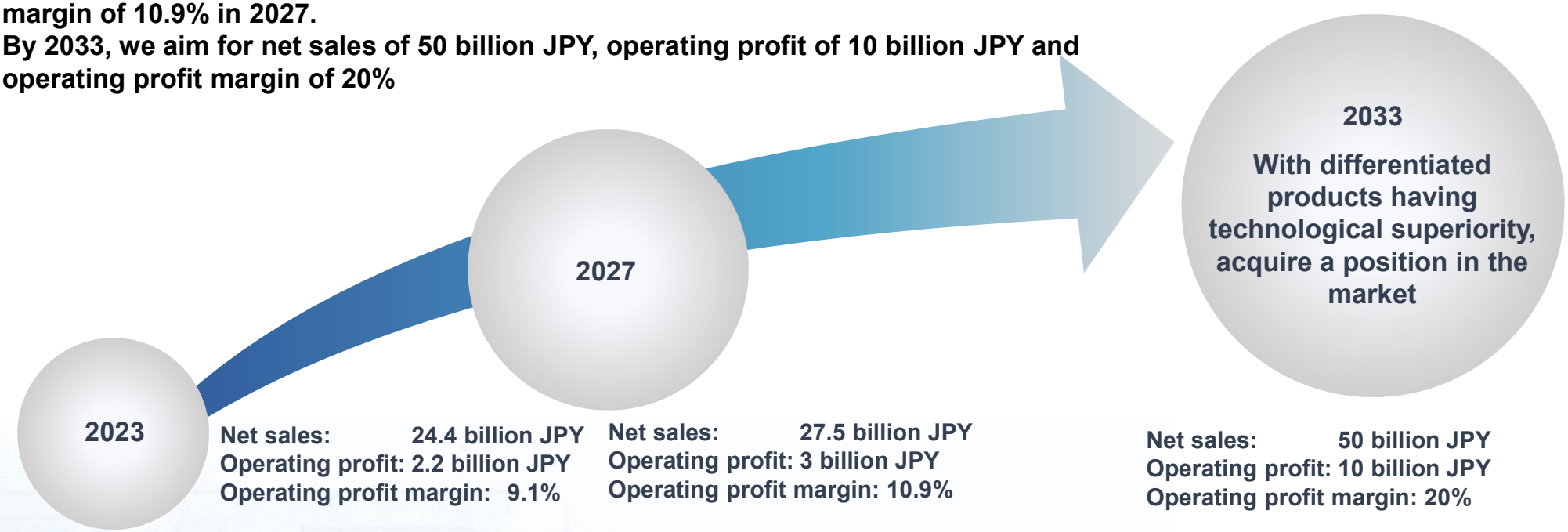


* Figures for 2019 and before have not been audited by an audit firm and are provided for reference only.

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Medium- to Long-Term Numerical Targets and Strategies on Four Axes

Considering the market environment, aim for sales of 27.5 billion yen, operating profit of 3 billion yen, and operating profit margin of 10.9% in 2027.
By 2033, we aim for net sales of 50 billion JPY, operating profit of 10 billion JPY and operating profit margin of 20%

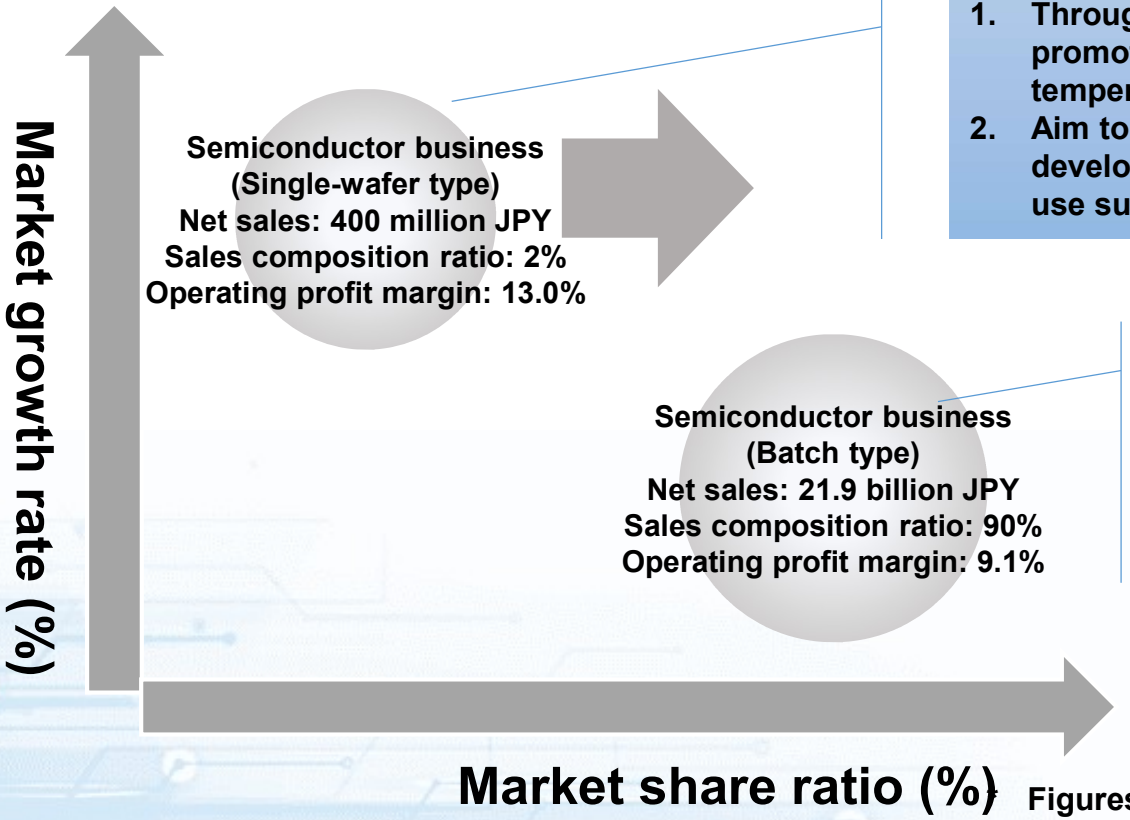


Product Strategy	Area Strategy	Organization Strategy	Manufacturing Strategy
• Batch-type cleaning equipment Promote high customizability in configuration and number of processing chambers • Single-wafer-type cleaning equipment Promote the capability of handling high-temperature, high-viscosity chemicals for differentiation • GX measures Take GX measures such as development of cleaning equipment that does not use sulfuric acid	• Major markets (South Korea, China and Taiwan): Promote transaction strengthening through existing relationships • U.S. market: Establish a local subsidiary to focus on customer development, especially in the “legacy semiconductor areas” • Japanese market: Strengthen development of manufacturers of automotive semiconductors, where Japan has a strong advantage, and manufacturers returning to the Japanese market	• Establishment of the System Design Department J.E.T.’s strengths are high customizability and technology of high-temperature, high-viscosity processing. Develop a top-level technical sales force under the guidance of CEO Bouno to achieve high-quality proposal-based sales • Strengthening of sales: First entry into the U.S. and first entry into Japan in 15 years. Develop customers based on differences in business culture	• Strengthening of supply chain In the semiconductor industry, which is strongly affected by economic fluctuations, flexible production capacity is essential. Strengthen relationships with partners and promote fabless operations • Construction of a new plant: Build a new plant to expand production capacity, improve production efficiency, and strengthen R&D capability

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Strategy Organization of the Business Portfolio for Growth

While maintaining the market share of batch-type equipment, pursue growth with differentiated single-wafer cleaning equipment



1. Through joint development with Rapidus, promote the technical capabilities of high-temperature, high-viscosity processing
2. Aim to increase the market share by developing cleaning equipment that does not use sulfuric acid, etc.

Expand into the Japanese and U.S. markets in addition to major markets while promoting the high customizability

Figures are actual results for FY2023

- The market for batch-type cleaning equipment is expected to maintain a certain market size and grow moderately in line with the growth of the semiconductor market.
  We have an 11% share of the global market and aim to continue to expand the market share ratio.
- Single-wafer cleaning equipment is likely to remain the primary cleaning equipment in the future and the market is expected to grow significantly with the growth of the semiconductor market.
  We aim to expand our market share through the development and sale of single-wafer cleaning equipment capable of high-temperature, high-viscosity processing.

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Product Strategy

Develop single-wafer-type cleaning equipment leveraging our technological superiority

New HTS

1. **Capability of handling processes other than sulfuric acid**
2. **Different product models offered for different chemical solutions (processes)**
3. **Lateral expansion of phosphoric acid based on track record in Japan**
4. **Lateral expansion of 03 based on track record in Taiwan**

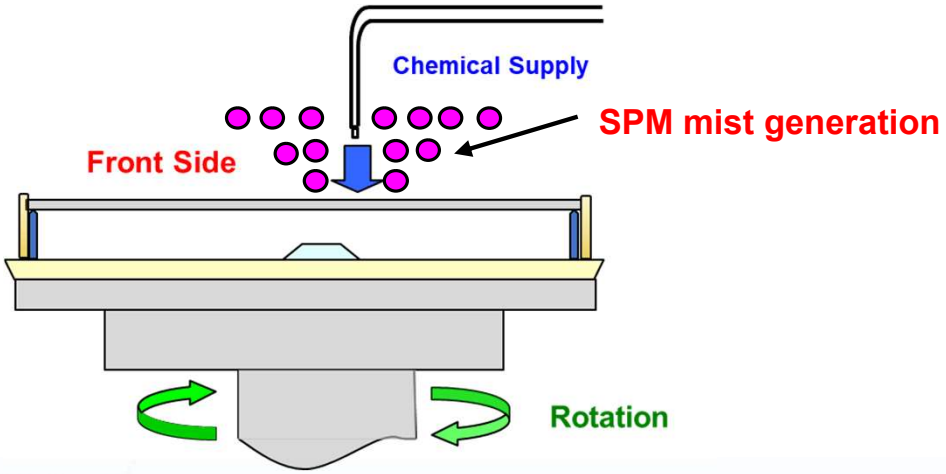


HTS-300

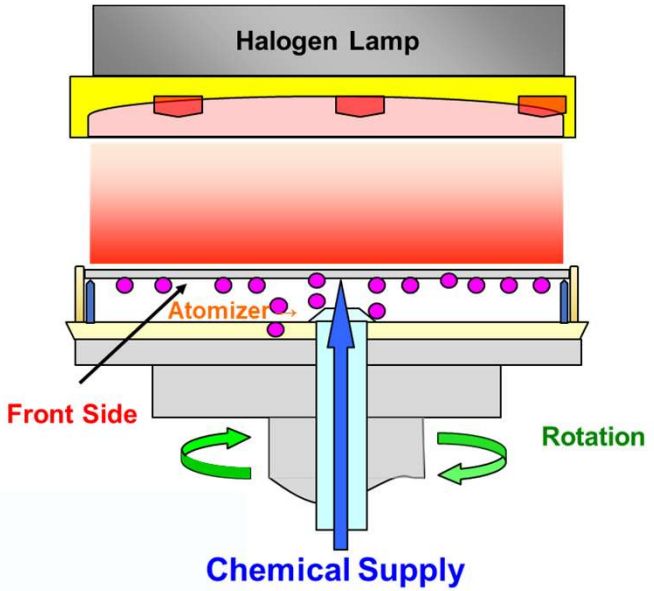
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J.E.T. Single-Wafer-Type Equipment Advantages

Company A/B single-wafer-type SPM system



J.E.T. single-wafer-type SPM system (HTS -300)



[Competitors' specifications]

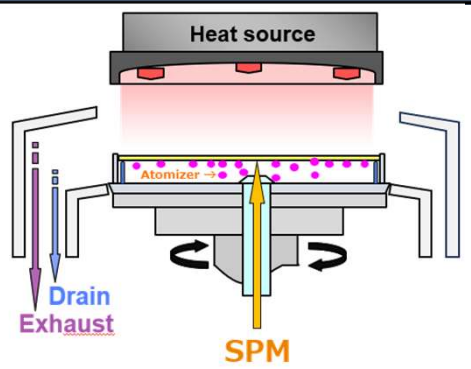
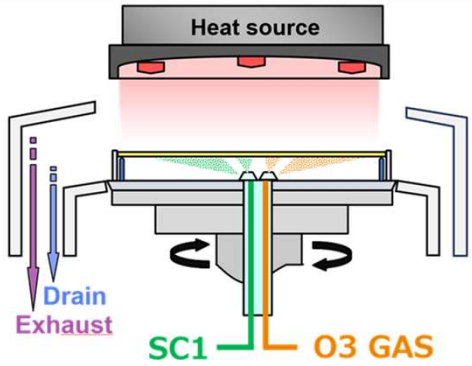
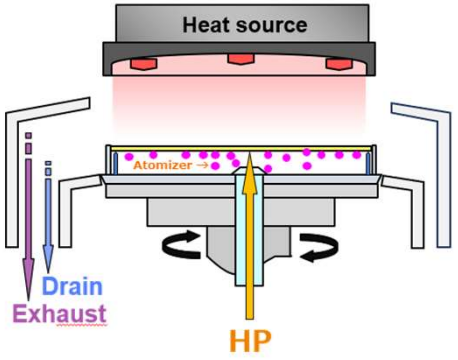
- Uses chemical reaction heat (150 to 200°C)
  - ➡ Difficult to maintain high temperature even when applying chemicals continuously
- Process time: 5min/Wafer
  - ➡ Amount of required chemicals: 3,000 ml/Wafer (since continuous application of chemicals for 5 minutes is necessary)
- SPM mist generates more particles

[JET specifications]

- Raising the temperature with halogen lamps (200 to 240°C)
  - ➡ Easy to maintain the high temperature
- Process time: 0.5min/Wafer
  - ➡ Amount of required chemicals: 150 ml/Wafer (About 1/20 of the amount used by competitors)
- Turn the wafer over so that the processing surface faces downward before applying atomized chemicals to prevent diffusion of SPM mist thereby suppressing particle generation

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Different processes of the J.E.T. Single-Wafer-Type Equipment

Type of chemicals	JET's Equipment	Illustrative drawings	Features and Performance
SPM(H2SO4) Resist stripping after high dose implantations Resist stripping after dry etching of P-SiN	**HTS** HTS-300		**Reduction of used chemical amount** • Reduces the amount of chemicals to 1/20 compared with competitors through significant shortening of process duration • High resist stripping rate is achieved with temperature controlled by heater Enables efficient processing • Suppress particle generation due to free falling of the removed resist
O3 GAS Resist stripping after high dose implantations Resist stripping after dry etching of P-SiN	**EcO3** OMR-3000		**Less environmental impact as well as low running costs** • Leveraging the structure of single-wafer-type SPM tools, processing with O3 gas has been realized. • Using O3 gas enables a process similar to SPM while mitigating the environmental impact • SC1 treatment in a single process module is possible since no by-products are formed by reaction of acids and alkalis.
HP(H3PO4) Removal of front side SiN	**Rush** HPR-3000		**First ever high temperature, high etching rate process with a single-wafer-type tool** • JET's patented technology enables state-of-the-art nitriding film processing in a single-wafer-type tool. • High wafer uniformity is realized • High etching rate is achieved by maintaining high temperatures
HP(H3PO4) Removal of back side SiN	**Rush** HBE-3000		

Patent: No. 5079145, No. 5165131

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Development work from Rapidus

- Rapidus entered a strategic partnership with IBM for the development and production of 2-nm semiconductors.
- Rapidus aims to achieve “semiconductor manufacturing faster than any other companies” in high-mix, low-volume production with a focus on using only single-wafer-type tools
- Manufacturing equipment is basically from IBM’s line but, for the phosphoric acid etching process, IBM’s line does not have a single-wafer type, requiring separate development (underway by J.E.T.)
- With the R&D phase (α machine) completed, it is currently in the R&D phase for prototype equipment (β machine) production, and will be delivered in 2025.
- We aim to deliver the equipment to mass production lines in 2027.



Rapidus Chitose Plant (IIM)
Construction started in September 2023
Prototype production line scheduled for launch in 2025 and mass production line in 2027



HTS-300

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BW3500 (1)

Twenty years have passed since the development of the mainstay BW3000 and BW3500 has been developed as a successor model to better meet customer needs

→ Capable of 28-nm and larger processes, the focus of investment in the future

→ Replacing competitors' products for RCA cleaning in mind

Improvements from BW3000

1. **Reduced footprint (15-16% reduction in equipment area and 20% reduction in overall equipment length)**
2. **Adopting a new transfer method (Transfer by Moving/Single Lifter in addition to transfer arm)**
3. **Environmental and safety measures (Provision of dedicated OHT port and improvement of airtightness to reduce leaking out of chemical atmosphere)**
4. **Damage prevention measures (adoption of resin tanks)**
5. **Improved operability (a large, color operation screen with more information)**

In addition, one-bath processing, metal ion measures, new exhaust system, reduced chemical usage, improved throughput and a new drying system have been adopted

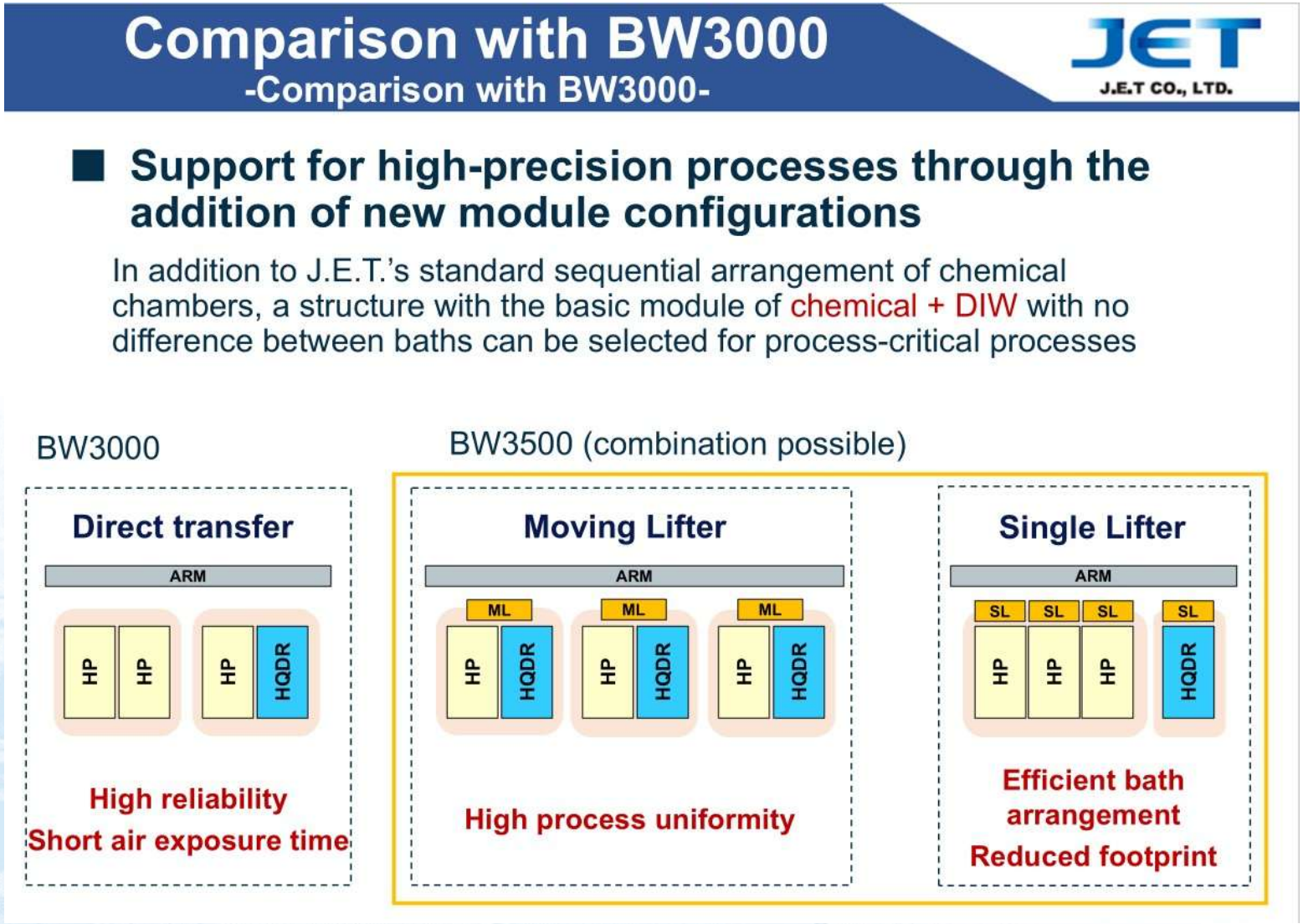


BW3500

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BW3500 (2)

Features the capability of high-precision processes



Source: J.E.T.'s sales data

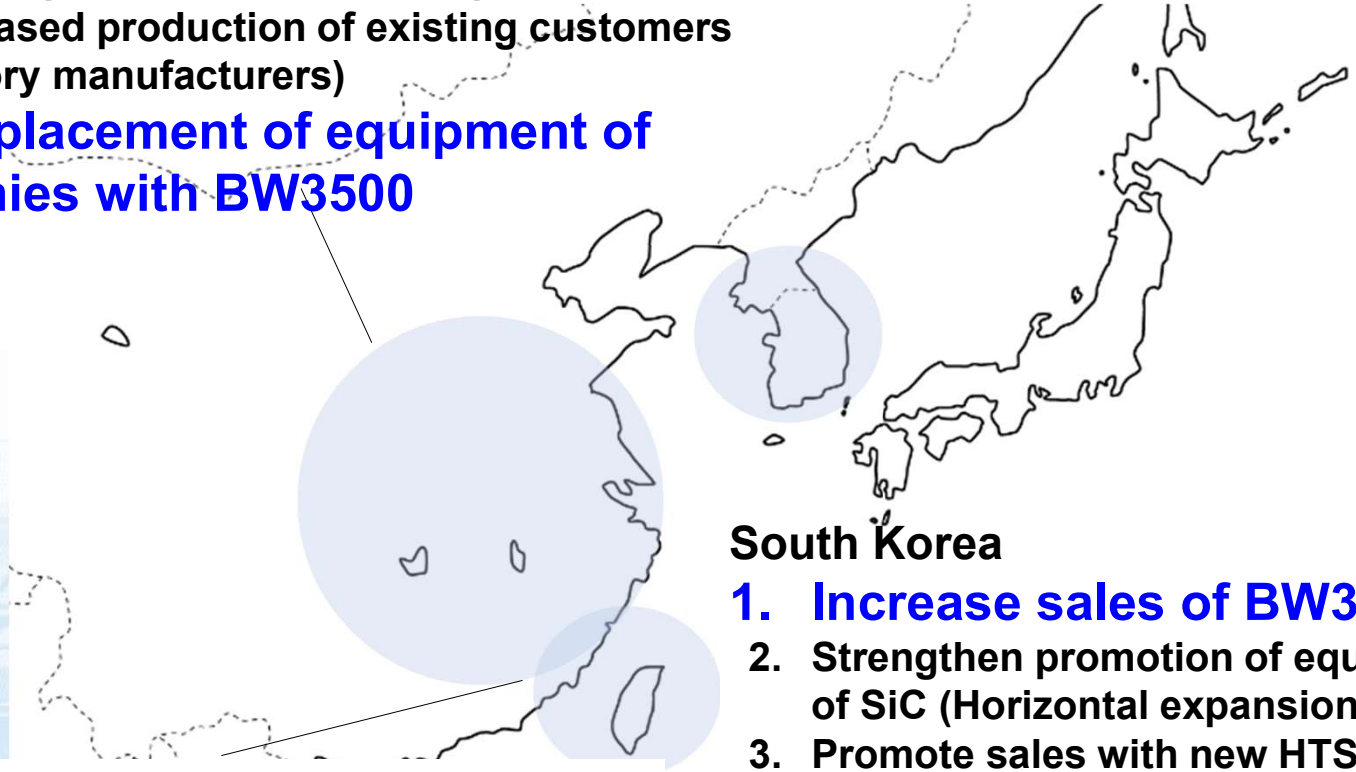
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BW3500 (3) Currently accepting orders and inquiries in China and Korea

Currently accepting orders and inquiries in China and Korea

China

1. Maintain relationships with the SMIC Group
2. Respond to increased production of existing customers (foundries, memory manufacturers)
3. **Accelerate replacement of equipment of other companies with BW3500**



South Korea

1. **Increase sales of BW3500 at Samsung**
2. Strengthen promotion of equipment capable of SiC (Horizontal expansion to other areas)
3. Promote sales with new HTS

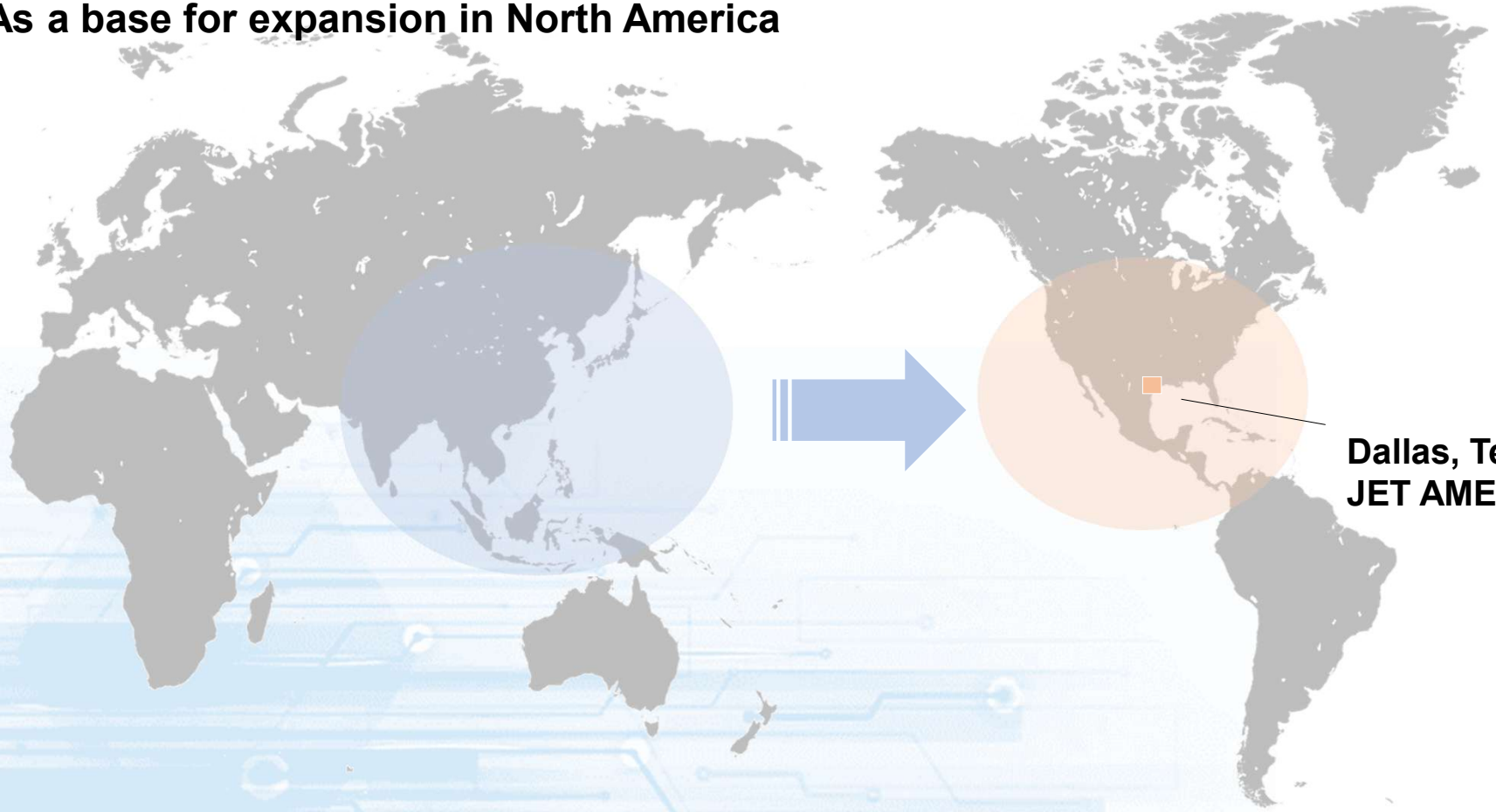
Taiwan

1. Give priority to promotion of HTS/Rush for TSMC (Horizontal expansion to other areas)
2. Maintain relationships with existing customers
3. **Accelerate replacement of equipment of other companies with BW3500**

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Area Strategy　Market Development in North America

Established JET AMERICA INC. as a subsidiary in North America to respond to changes in the geopolitical environment
As a base for expansion in North America



Dallas, Texas
JET AMERICA INC.

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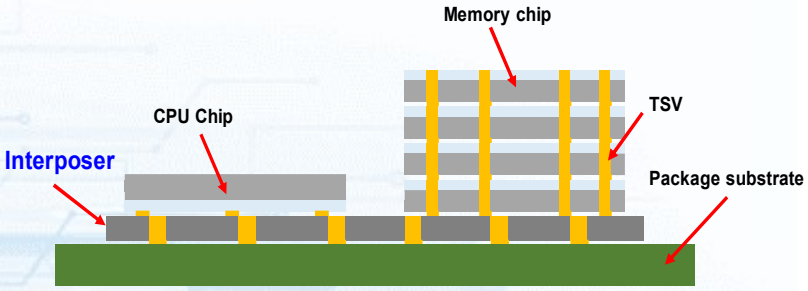
U.S. subsidiary, Received Orders for Interposer Cleaning Tools

U.S. subsidiary, JET AMERICA INC., was established in January 2024 in Texas where Texas Instruments (TI) and other companies are headquartered.
While beginning to develop customers in a legacy semiconductor area, orders for cleaning equipment for "interposers," which electrically connect semiconductor chips and substrates, have been received and shipped, with local delivery and start-up planned for 2025.



Interposer (Wiring circuit board)

Originated from Latin, meaning "put in between."
A component that plays an extremely important role as a relay component in the technology of assembling semiconductor chips like Lego blocks (chiplet).
Essential for 2.5D and 3D packages, which will be the basic structure for advanced packaging of AI semiconductors.





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3. Toward Sustainability Management

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Messages for Sustainability Management

As a publicly listed company, we need to make a firm commitment to sustainability management.
Announced the Sustainability Management Policy on December 13, 2024 that included the strengthening of the corporate structure at this time when the company's performance is sluggish.

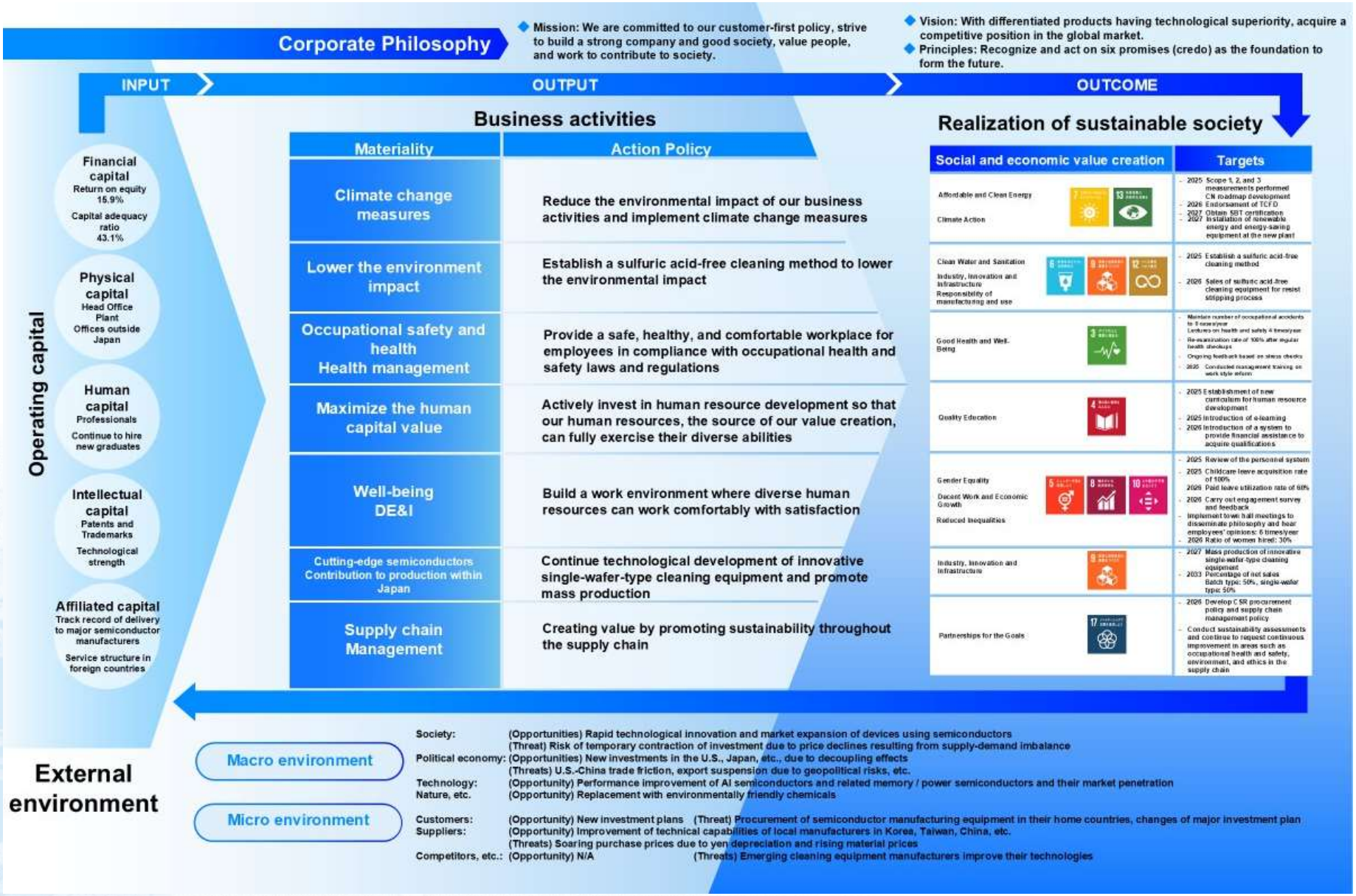
We are committed to contributing to society by developing alternative semiconductor cleaning equipment using a process with low environmental impact.

In addition, we have a plan to construct a new factory to respond to the increase in sales over the past few years. We intend to improve productivity and accelerate research and development by introducing cutting-edge technologies, and at the same time, as a contribution to social value, we intend to make the factory environmentally friendly and able to coexist with the local community.

Based on the idea that a company is only as good as its people, we have hired 5 to 7 new graduates every year since 2017, and, in addition to that, we have been actively recruiting new mid-career employees. We will introduce a personnel system that includes a new human resources training system, aiming to quickly turn human resources into a competitive force.

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Sustainability Management Policy



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Materiality (Key Issues) and Action Policies

Materiality (Key Issues)	Action Policy
1. Climate change measures	Reduce the environmental impact of our business activities and implement climate change measures
2. Lower the environment impact	Establish a sulfuric acid-free cleaning method to lower the environmental impact
3. Occupational Health and Safety, and Health Management	Provide a safe, healthy, and comfortable workplace for employees in compliance with occupational health and safety laws and regulations
4. Maximize the human capital value	Actively invest in human resource development so that our human resources, the source of our value creation, can fully exercise their diverse abilities
5. Well-being, DE&I Note 1)	Build a work environment where diverse human resources can work comfortably with satisfaction
6. Contribute to production of cutting-edge semiconductors in Japan	Continue technological development of innovative single-wafer-type cleaning equipment and promote mass production
7. Supply chain management	Creating value by promoting sustainability throughout the supply chain

Note (1) What is Well-being? ➡ "The state of being physically, mentally, and socially healthy."
What is DE&I (Diversity, Equity & Inclusion)? ➡ A concept that aims to create an environment where "diversity" is "accepted and included" and where people can grow while respecting each other under the provision of "fair" opportunities for each individual.

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Appendix

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Company Overview

Engaged in development, manufacture, sales, and after-sales service of semiconductor cleaning equipment

Our forerunner is S.E.S. Co., Ltd. (“S.E.S.”), which commenced civil rehabilitation proceedings during the semiconductor recession in the aftermath of the collapse of Lehman Brothers and subsequently went into bankruptcy

To take over S.E.S.’s outstanding technologies for semiconductor cleaning equipment, we were established on April 24, 2009 as a wholly owned subsidiary of ZEUS CO., LTD. (“ZEUS”), a Korean company that was a sales agent of S.E.S. In May 2009, we launched our business as we acquired S.E.S.’s Okayama Plant etc., in a business transfer

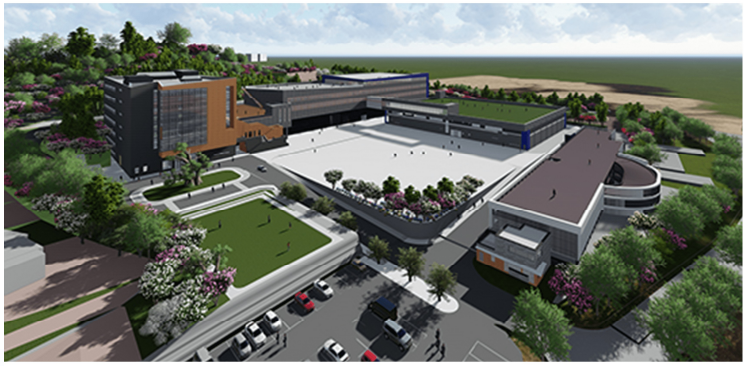
- Company Overview

Name	J.E.T. Co., Ltd.
English Name	J.E.T. Co., LTD.
Establishment	April 2009
Capital	1,848 million JPY (as of December 31, 2024)
Address TEL	6078, Shinjo Kanayama, Satosho-cho, Asakuchi-gun, Okayama 0865-69-4080
Representative	Masayuki Bouno, Representative Director and CEO
Number of Employees	169 employees 293 employees, * Total number of employees, including consolidated subsidiaries (as of December 31, 2024)
Business summary	Development, manufacture, sales and after-sales service of semiconductor cleaning equipment
Main Customers	Samsung Electronics (South Korea), SMIC (China)

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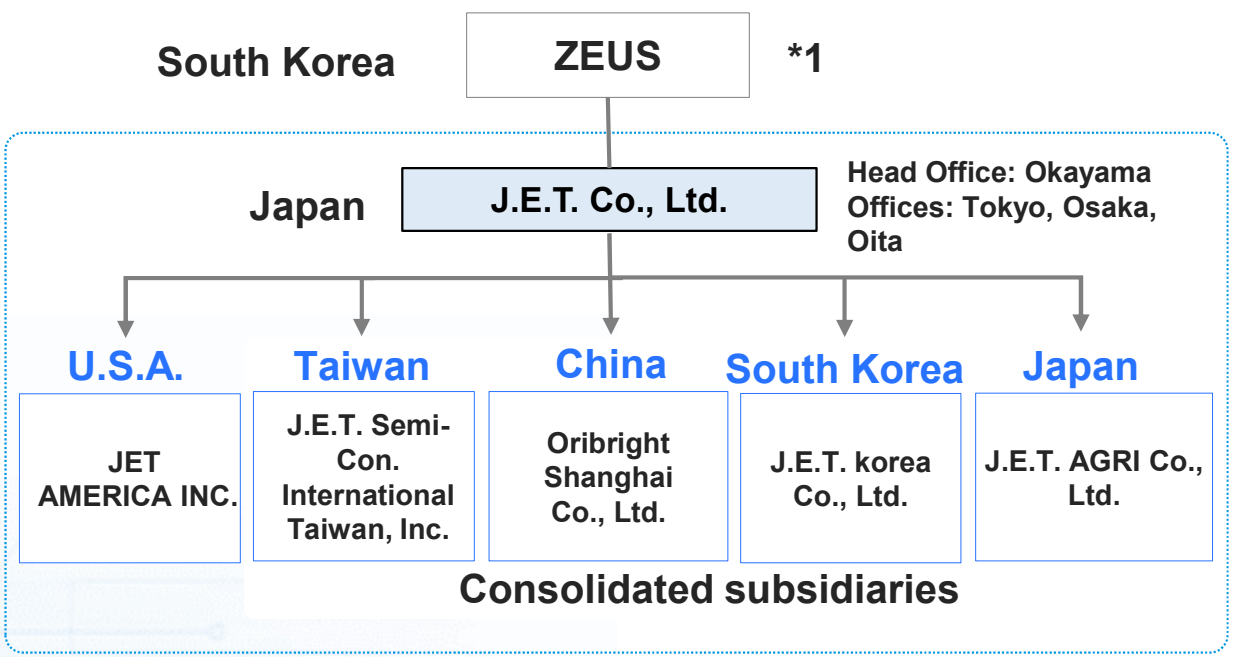
Group Relationship Diagram

Our business is separate from that of ZEUS, our parent company. We have no competitive relationship with them, and our management aims to be highly independent of them by eliminating the acceptance of officers and employees on secondment.



Address: Republic of Korea
Republic of Korea
Capital: 15,530,995 thousand KRW
Description of business: Manufacture and sales of various manufacturing equipment for semiconductors and liquid crystal
Percentage of voting rights held in our company: 66.3% (direct)
Relationship with the related party: Business transactions
Description of transactions: Sales and purchase of parts, materials, etc., and outsourcing of equipment manufacturing operations between the two companies, and payment of sales commissions, etc., from us to ZEUS

Relationship Diagram



*1: Listed on KOSDAQ (a stock exchange in South Korea)

* Until the end of April 2022, we had one part-time director from ZEUS. From May 2022 onward, we have no officers or employees on secondment or otherwise accepted from ZEUS.

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Offices

- Offices in Japan
- Offices outside Japan



Office in South Korea:
23 employees

J.E.T. korea Co., Ltd.

Oribright Shanghai Co., Ltd. Beijing Office

Oribright Shanghai Co., Ltd. Wuxi Office

Oribright Shanghai Co., Ltd. Hefei Office

Oribright Shanghai Co., Ltd. Xi'an Office

Oribright Shanghai Co., Ltd. Guangzhou Office

Oribright Shanghai Co., Ltd. Shanghai Head Office



Offices in China:
73 employees

* Some offices in China have been omitted.

Osaka Office (*2)

Tokyo Office (*1)

J.E.T. Co., Ltd.

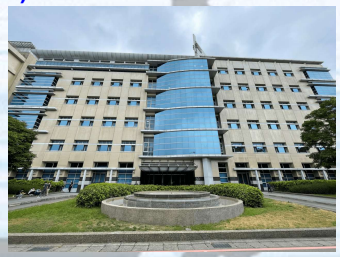
Kyushu Branch (*1)

- Head Office
- Kasaoka Farm (*3)

Head Office



J.E.T. Semi-Con. International Taiwan, Inc.
(HEAD Office) Taiwan Head Office



Office in Taiwan:
21 employees

J.E.T. Semi-Con. International Taiwan, Inc.
(Singapore branch) Singapore Branch

Singapore: 3 employees



JET AMERICA INC.

Office in the United States:
3 employees

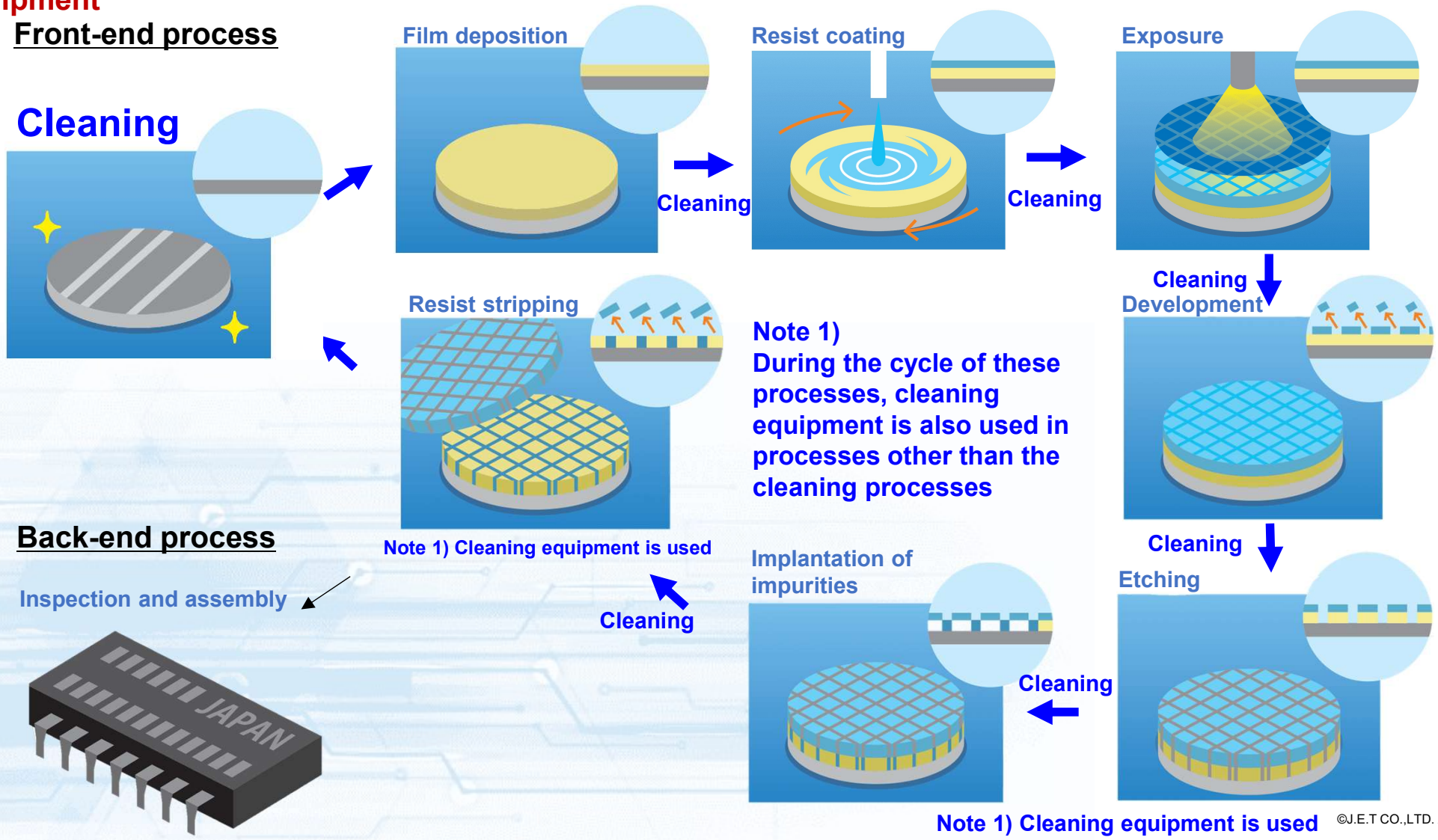
*1 At Tokyo Office and Kyushu Branch, we provide field services to our customers.
*2 Osaka Office is in charge of LIB product sales.
*3 At Kasaoka Farm, J.E.T. AGRI Co., Ltd., our consolidated subsidiary, grows tomatoes.

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Semiconductor Manufacturing Process
Front-end Process

Cleaning is extremely important in the front-end process (which includes more than 500 steps) of semiconductor manufacturing

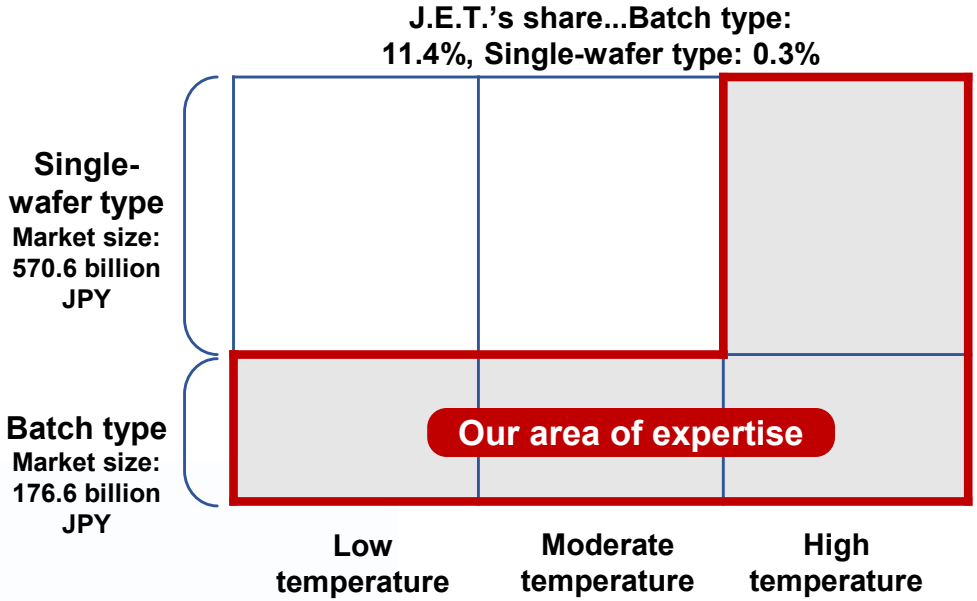
30–40% (based on the number of steps) of the front-end process is estimated to involve the use of cleaning equipment



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Semiconductor Cleaning Equipment　Batch Type and Single-Wafer Type—Our Area of Expertise

		Batch-type cleaning equipment	Single-wafer-type cleaning equipment
Summary		25 to 50 wafers are batch-cleaned	Wafers cleaned one by one
Advantage		It is highly productive	Precision cleaning is possible
Disadvantage		It can easily pick up wafer dust	It causes low productivity
Current status		Due to its superior productivity, maintains a certain share	Currently the mainstream cleaning equipment
High-temperature, high-viscosity processing	Features	Easy to maintain process temperature	Difficult to maintain process temperature
	Sulfuric acid	++ (mainstream)	+ (partially supported)
	Phosphoric acid	++ (mainstream)	- (not supported)
Market size (2023/Global)		152.5 billion JPY (J.E.T.'s share: 14.3%)	598.6 billion JPY (J.E.T.'s share: 0.1%)



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Competitive Landscape and Differentiators

We believe that Japanese companies have had more than a 70% share in the semiconductor cleaning equipment market since the 2000s, and Company A and Company B have a particularly strong presence

		J.E.T.	Company A	Company B
Company Size (Net Sales/Operating Profit for Recent Fiscal Year)		24.4 billion JPY (2.2 billion JPY)	460.8 billion JPY (76.5 billion JPY)	2,209 billion JPY (617.7 billion JPY)
Market Share (Market Size in FY2022)	Batch type (176.6 billion JPY)	11.4% (20.2 billion JPY)	47.8% (83.5 billion JPY)	28.8% (50.8 billion JPY)
	Single-wafer type (570.6 billion JPY)	0.3% (1.1 billion JPY)	48.5% (217 billion JPY)	28.3% (152.3 billion JPY)
Technologies	RCA Cleaning (hydrofluoric acid/ammonia water addition)	+	+++	++
	Sulfuric acid cleaning	+++	++	+
	Phosphoric acid cleaning	+++	++	+
	Others	++	+	++
Production Capacity		+ (Mass production capacity low)	+++ (Mass production capacity provided)	+++ (Mass production capacity provided)
Customizability		+++ (Strength in customizability)	+ (Strength in standardized equipment)	+ (Strength in standardized equipment)

Source: Ministry of Economy, Trade and Industry "Strategy for Semiconductors and the Digital Industry, June 2023"; evaluation is based on our own recognition

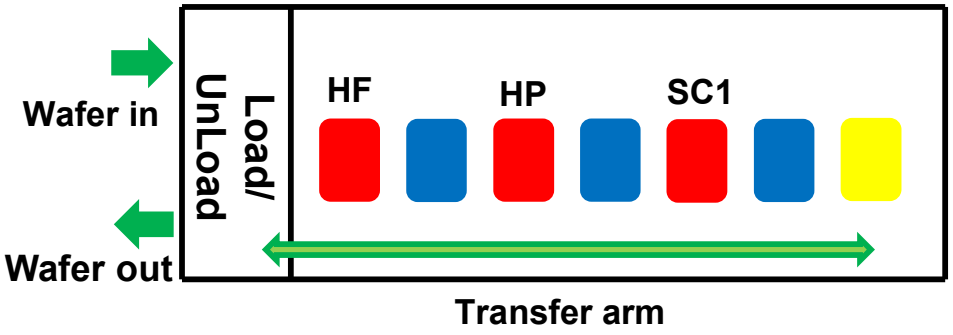
- Our competitors are large companies with sales in the hundreds of billions of JPY to trillions of JPY and their strength lies in their ability to mass produce high-quality, standardized equipment
- Although we lack mass production capabilities, we entered into a niche market area, which larger companies would have difficulty accessing, involving complex high-temperature and high-viscosity processing with highly customizable tools leveraging our flexible operational abilities, and have obtained a share of the market.

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JET batch-type equipment advantages
➡ The only equipment with F-Type

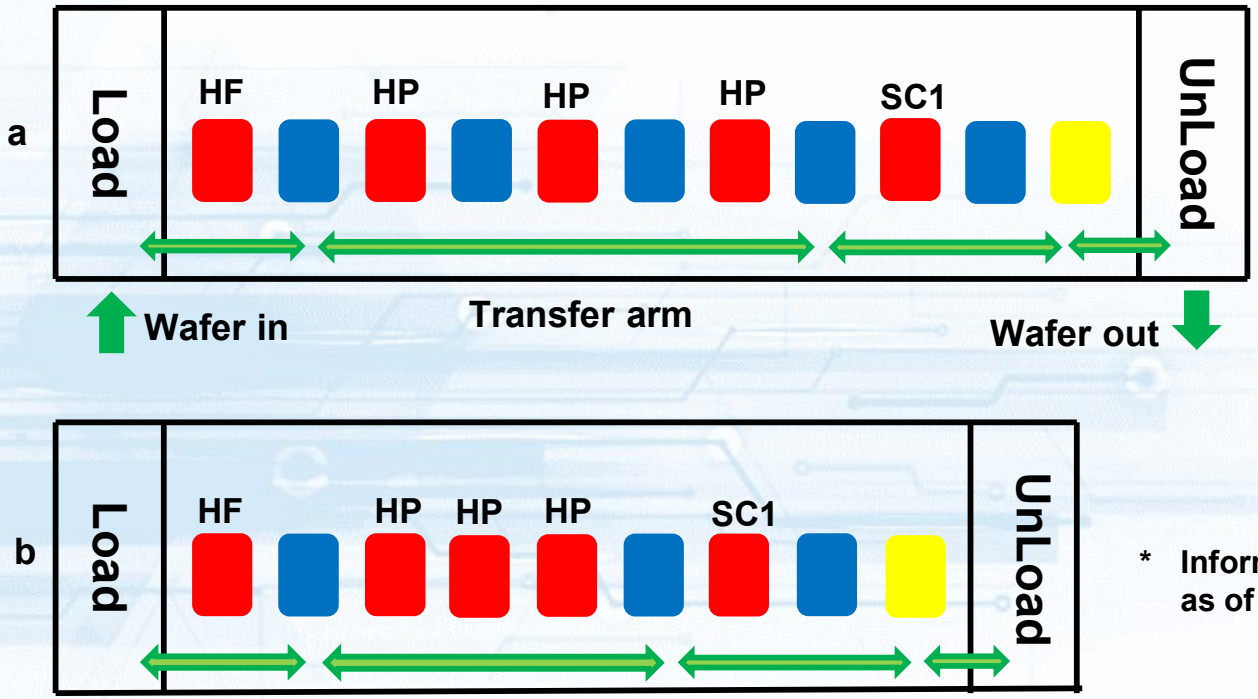
Chemical chamber
Water washing chamber
Dryer

I-Type Company A/ Company B/ J.E.T.



Features
- Compact
- Processing chamber: 8 chambers max.
  (The arm moves from side to side, causing jams)
- Throughput: 250 wafers/h max.

F-Type Made by J.E.T. only



Features
- A little large
- Processing chamber: 14 chambers max.

(Because the one-way arm prevents jams)
- Can be selected from a or b
- b enables sequential arrangement of chemical chambers
- Often used for sulfuric acid/phosphoric acid cleaning at high temperatures
- **Throughput: 500 wafers/h max.**

* Information is based on our own understanding as of December 2023.

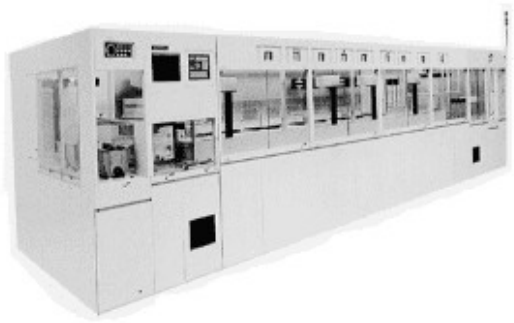
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Our Main Products (1)

	BW3000	BW3700
		
Cleaning type	Batch-type cleaning equipment Compatible with 300-mm wafers	Batch-type cleaning equipment Compatible with 300-mm wafers
Features	◎ Flexible configuration to meet customers' requirements (the arrangement and the number of cleaning chambers can be changed according to the customer's request). ◎ Improvement in production efficiency ◎ High-Speed LD/ULD compatible with 500 WPH ◎ Small equipment footprint: The number of installations in a plant can be increased. ◎ Reduction in carbon dioxide ◎ Controlled gas flow ◎ Reduced start-up time by standardized specifications ◎ Comply with SEMI standard ◎ Compatible with EES (EDA or TDI)	◎ Small equipment footprint: The number of installations in a plant can be increased. ◎ Stabilization of throughput of each processing chamber through individual piping in the exhaust system ◎ Processing with a 7-mm pitch between wafers ◎ Reduction in particle generation (fine dust) by achieving a reduction of a contact point of wafers ◎ Reduction in bubble generation ◎ Improved efficiency in liquid replacement by a reverse flow system ◎ Improved stability in concentration ◎ Compatible with a wide variety of processing chambers ◎ Compatible with the 1 chemical solution plus 1DIW configuration
Price range (average unit price) (millions of JPY)	210–400	320–560

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Our Main Products (2)

	BW2000	HTS-300
		
Cleaning type	Batch-type cleaning equipment Compatible with 200-mm wafers	Single-wafer-type cleaning equipment Compatible with 300-mm wafers
Features	◎ High production efficiency ◎ High cleaning capability ◎ Small footprint ◎ Flexible configuration to meet customers' requirements (the configuration and the number of cleaning chambers can be changed.)	◎ Processing with chemical solution of 150 cc (minimum) is possible ◎ High processing temperature of up to 240° C is possible ◎ Stripping in 30 seconds (minimum) is possible ◎ Prevention of diffusion of fumes (chemical solution vapor) by turning the wafer over
Price range (average unit price) (millions of JPY)	150–210	330–540

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Notes

Precautions for handling this document

- This document has been prepared based on the Consolidated Financial Results announced on February 7, 2025.
- The forecasts and forward-looking statements contained in this document are based on information currently available to us and do not guarantee or promise the accuracy or completeness of such information. In addition, changes in economic trends, industry competition, markets and systems may cause significant changes in the outlook.
- Figures in this document are rounded down to the nearest unit. Percentages are rounded off to the nearest unit.

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